

### General Description

The Sanrise SRT045N012H is a low voltage power MOSFET, fabricated using advanced split gate trench technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and synchronous rectification.

The SRT045N012H break down voltage is 45V and it has a high rugged avalanche characteristics. The SRT045N012H is available in PDFN5\*6 package.

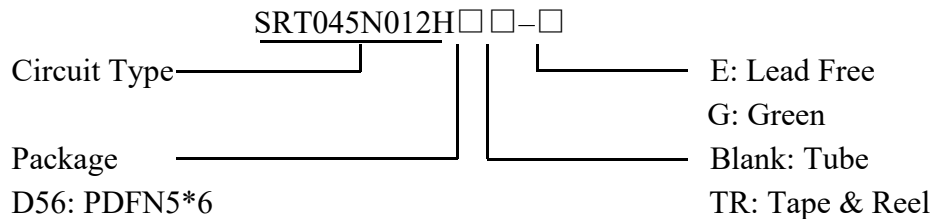
### Features

- Ultra Low  $R_{DS(ON\_TYP)} = 1.07m\Omega @V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g=73nC$  typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved
- Non-automotive Qualified

### Application

- Server/Telecom
- DC/DC Converter
- High Power Supply
- E-Tools
- BMS

### Ordering Information



### Symbol

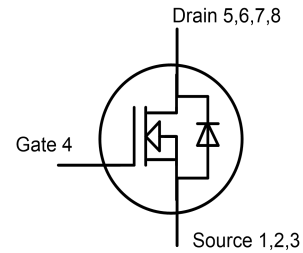
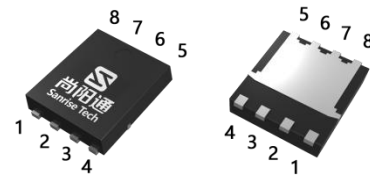


Figure 1 Symbol of SRT045N012H

### Package Type



PDFN5\*6

Figure 2 Package Type of SRT045N012H

Package	Part Number	Marking ID	Packing Type
PDFN5*6	SRT045N012HD56TR-G	SRT045N012HD56G	Tape & Reel

## Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	45	V
Gate-Source Voltage	$V_{GSS}$	±20	V
Continuous Drain Current, Silicon	$I_D$	$T_C=25^{\circ}C$	228
		$T_C=100^{\circ}C$	144
Pulsed Drain Current (Note 3)	$I_{DM}$	912	A
Power Dissipation ( $T_C = 25^{\circ}C$ )	$P_D$	131	W
Avalanche Destructive Energy, Single Pulse (Note 5)	$E_{AS\_Limit}$	625	mJ
Avalanche Energy, Single Pulse (Note 4)	$E_{AS}$	121	mJ
Avalanche Energy, Repetitive (Note 3)	$E_{AR}$	0.3	mJ
Avalanche Current, Repetitive (Note 3)	$I_{AR}$	50.0	A
Continuous Diode Forward Current	$I_S$	228	A
Diode Pulse Current	$I_{S,PULSE}$	912	A
Operating Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)	$T_{LEAD}$	260	°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Current Limited by Package.
3. Repetitive Rating: Pulse width limited by maximum junction temperature
4.  $I_{AS}= 22A$ ,  $V_{DD}= 20V$ ,  $R_G= 25\Omega$ , Starting  $T_J= 25^{\circ}C$
5.  $I_{AS\_Limit}= 50.0A$ ,  $V_{DD}= 20V$ ,  $R_G= 25\Omega$ , Starting  $T_J= 25^{\circ}C$

## Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{thJC}$			0.95	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$			50	

## Electrical Characteristics

**1.2mΩ, 45V, N-Channel Power MOSFET**
**SRT045N012H**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	45			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=45V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			200	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-200	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	2.0	3.0	4.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=60A$		1.07	1.2	mΩ
Gate Resistance	$R_G$	f=1MHz, Open Drain		1.1		Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=20V, V_{GS}=0V, f=1MHz$		5.2		nF
Output Capacitance	$C_{OSS}$			2.0		nF
Reverse Transfer Capacitance	$C_{RSS}$			125		pF
Effective output capacitance, energy related <sup>NOTE5</sup>	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 20V$		3.1		nF
Effective output capacitance, time related <sup>NOTE6</sup>	$C_{O(tr)}$			3.8		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=20V, I_D=50A, R_G=1.6\Omega, V_{GS}=10V$		18		ns
Rise Time	$t_r$			50		
Turn-off Delay Time	$t_{d(off)}$			54		
Fall Time	$t_f$			12		
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	$Q_{gs}$	$V_{DD}=20V, I_D=50A, V_{GS}=0 \text{ to } 10V$		24		nC
Gate to Drain Charge	$Q_{gd}$			13		
Gate Charge Total	$Q_g$			73		
Gate Plateau Voltage	$V_{plateau}$			4.9		V
Gate Charge Total, sync FET	$Q_g$	$V_{DD}=0.1V, V_{GS}=0 \text{ to } 10V$		69		nC
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=50A$		0.84	1.0	V
Reverse Recovery Time	$t_{rr}$	$V_R=20V, I_F=50A, dI_F/dt=100A/\mu s$		62		ns
Reverse Recovery Charge	$Q_{rr}$			130		nC
Peak Reverse Recovery Current	$I_{rrm}$			4.3		A

Note:

- $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 20V
- $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 20V



Sanrise Technology Limited Company

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